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SERIAL NUMBER 10/525,996	FILING OR 371(c) DATE 02/28/2005 RULE	CLASS 257	GROUP ART UNIT 2811	ATTORNEY DOCKET NO. 1217-050618
APPLICANTS Hideo Senoo, Saitama, JAPAN; Koichi Nagamoto, Saitama, JAPAN; Katsuhiko Horigome, Saitama, JAPAN; Hitoshi Ohashi, Saitama, JAPAN;				
** CONTINUING DATA ***** This application is a 371 of PCT/JP03/10570 08/21/2003				
** FOREIGN APPLICATIONS ***** JAPAN 2002-249622 08/28/2002				
Foreign Priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 (a-d) conditions <input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after met Allowance Verified and Acknowledged		STATE OR COUNTRY JAPAN	SHEETS DRAWING 2	TOTAL CLAIMS 20
Examiner's Signature _____ Initials _____		INDEPENDENT CLAIMS 5		
ADDRESS Kent E Baldauf 436 Seventh Avenue 700 Koppers Building Pittsburgh ,PA 15219-1818				
TITLE Protective structure of semiconductor wafer, method for protecting semiconductor wafer, multilayer protective sheet used therein, and method for processing semiconductor wafer				
FILING FEE RECEIVED 1300	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit	